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Nomenclature Guides

Intersil Nomenclatures

ISL Types

PREFIX	ISL	X	XXXX	X	I	XX	X	XXX	Z	-T	SUFFIX/ POST PROCESSING/ SPECIAL SERVICES
<p>FAMILY DESIGNATOR</p> <p>1: DSL, RTC, Clocks, ATE 2: Reference, DCPs, Buffers, Precision Op Amp, Sensors 3: Interface, Data Communication 4: Analog Component Solutions 5: High Speed Amps, Switch/MUX, ADCs, DACs, Optical, Video, Telecom VoIP, DSP Function Specific 6: Desktop Power 7: Space, Auto 8: Analog Switches, General Purpose Power 9: Notebook, Handheld</p>											
<p>PART NUMBER</p> <p>3 to 5 Digits</p>											
<p>OPTION</p> <p>E: 15kV ESD Protected DCP Resistance Options W: 10k U: 50k T: 100k</p>											
<p>TEMPERATURE RANGE</p> <p>C: 0°C to +70°C (Commercial) D: 0°C to +85°C H: -10°C to +100°C (Hi-Temp Comm.) E: -20°C to +85°C (Extended Comm.) I: -40°C to +85°C (Industrial) A: -40°C to +105°C (Automotive) F: -40°C to +125°C (Full-range Industrial) P: -40°C to +130°C (Power Supply) M: -55°C to +125°C (Military) RHV: QML Class V RHQ: QML Class Q RHT: QML Class T</p>											
<p>PB-FREE OPTION</p> <p>Z: Pb-Free with Anneal (Anneal added after 01Mar05) ZA: Pb-Free with Anneal</p>											
<p>SPECIAL SELECTIONS</p> <p>Optional Characters to Denote Operating Conditions or Package Options:</p> <p>18: 1.8V 33: 3.3V EP: Enhanced Product (DSCC Vendor Item Drawing) EPZ: Enhanced Product w/100% Matte Tin Lead Finish</p>											
<p>OPTIONAL ELECTRICAL GRADE</p> <p>To Denote Speed or Precision Grading as Defined in Datasheet</p>											
<p>PACKAGE DESIGNATOR</p> <p>A: Shrink Small Outline Plastic (SSOP/QSOP) B: Small Outline Plastic (SOIC) BE: Exposed Pad SOIC (EPSOIC) C: Available D: Ceramic Dual-In-Line Metal Seal (SBDIP) E: Small Outline Transistor Plastic (SC-70) F: Ceramic Flatpack G: Available H: Small Outline Transistor Plastic (SOT-23) HT: Thin Small Outline Transistor Plastic (TSOT) I: Chip Scale Package (CSP) J: Ceramic Dual-In-Line Frit Seal (CERDIP) K: Ball Grid Array (FBGA/PBGA/LGA) KE: Heat Sink Ball Grid Array (HBGA) KV: Very Thin Fine Pitch BGA (VFBGA) L: Ceramic Leadless Chip Carrier (CLCC, SMD 0.5) M: Plastic Leaded Chip Carrier (PLCC) N: Thin Plastic Quad Flatpack (TQFP/LQFP) O: Do Not Use P: Dual-In-Line Plastic (PDIP) Q: Metric Plastic Quad Flatpack (MQFP/PQFP) R: Quad/Dual Flat No Lead (QFN/DFN) RO: Optical Quad/Dual Flat No Lead (OQFN/ODFN) ROM: Optical Quad/Dual Flat No Lead Module RT: Thin Quad/Dual Flat No Lead (TQFN/TDFN) RU: Ultra Thin Quad/Dual Flat No Lead (UTQFN/UTDFN/ePad UTQFN) RS: Top Exposed Pad QFN (TEPQFN) S: Header (TO-257) T: Metal Can (TO-39) U: Mini Small Outline Package (MSOP) UE: Thermally Enhanced Mini Small Outline Package (HMSOP) UO: Optical Mini Small Outline Package (OSOP) V: THIN Shrink Small Outline Plastic (TSSOP) VE: Thermally Enhanced Thin Shrink Small Outline Plastic (HTSSOP/EPTSSOP) W: Wafer Sale WMB: Wafer Sale With Solderable Metal Backing Layer XM: Die Sale, Military Visual (Condition B) XC: Die Sale, Commercial Visual XB: Die Sale, Bumped Die (FCP) Y: Available Z: Do Not Use</p>											
<p>SPECIAL SERVICES</p> <p>-T: Tape and Reel -T1: Tape and Reel -T2: Tape and Reel w/Vacuum Pack -T7: 7" Reel -TS: 7" Reel, 100 pc. -T7A: 7" Reel, 250pc. -T13: 13" Reel -T5: 500pc Tape and Reel -TK: 1,000pc Tape and Reel -T5K: 5,000pc Tape and Reel -Eval: Evaluation Boards -Eval*Z: Pb-Free Evaluation Boards -EC: Enhanced Commercial (Enhanced EOL, MIL-PRF-38535 Change Notice, Traceable to Wafer Lot)</p>											

EL Types

EL
PREFIX

1503
PART NUMBER

A
OPTIONAL SUFFIX OR PART VARIATION

I
TEMPERATURE RANGE

R
PACKAGE FAMILY

Z
PB-FREE OPTION
Z: Pb-Free Product
ZA: Pb-Free with Anneal

-T
SUFFIX/POST PROCESSING/SPECIAL SERVICES
-T: Tape and Reel
-T7: 7" Reel
-T7A: 7" Reel (250 pcs)
-T13: 13" Reel

TEMPERATURE RANGE

- C: (Commercial) 0°C to +70°C
- I: (Industrial) -40°C to +85°C
- M: (Military) -55°C to +125°C
- A: (Automotive) -40°C to +105°C
- D: 0°C to +85°C
- E: (Extended Comm) -20°C to +85°C

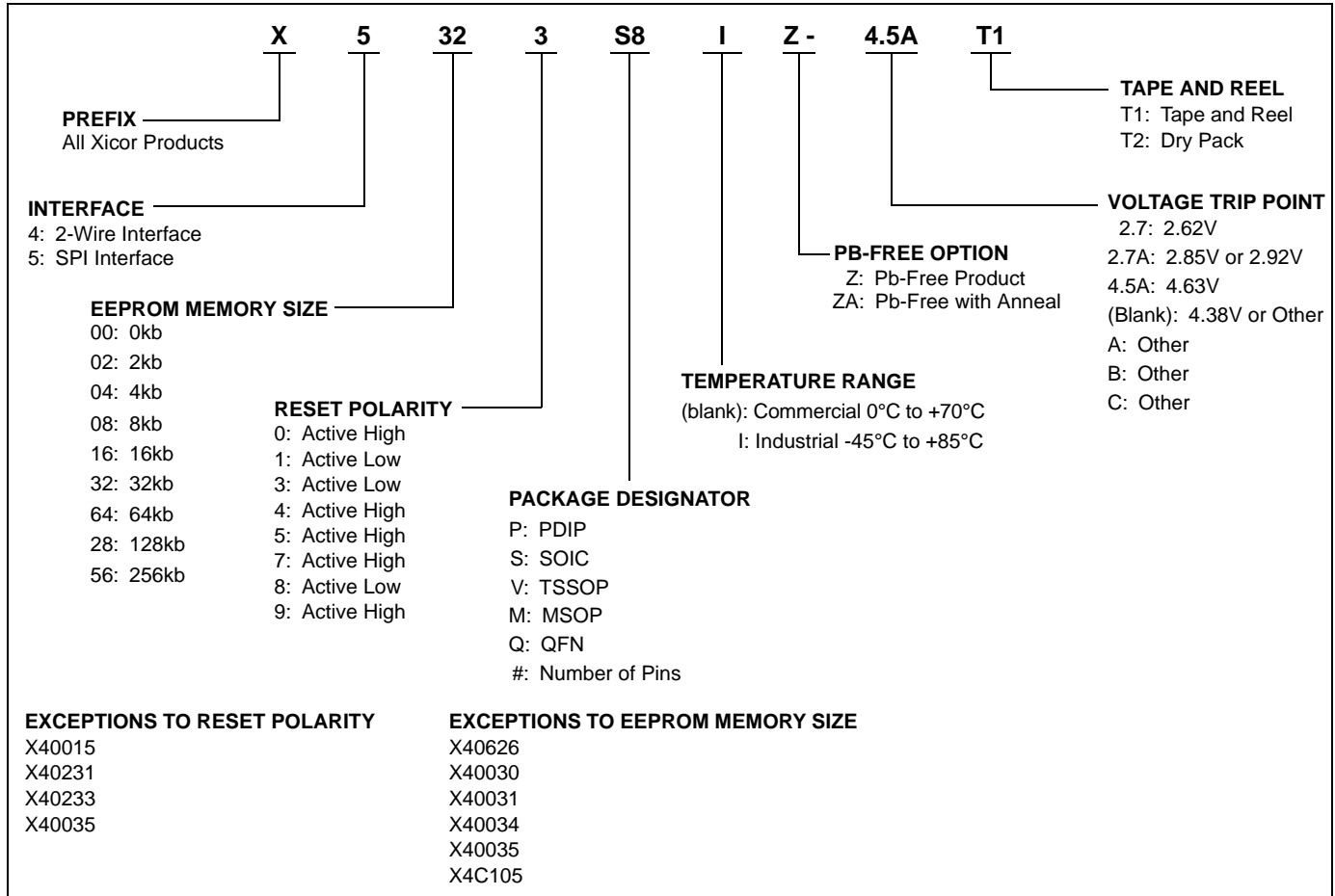
PACKAGE FAMILY

PACKAGE TYPE	PACKAGE DESIGNATOR
Bare Die	D
CerDip	J
QFN/DFN (Saw Singulate)	L
SO (0.300") and HSOP	M
PDIP	N
TSSOP (4.4 mm)	R
HTSSOP (4.4 mm)	RE
SO (0.150")	S
TO-220	T
QSOP	U
SOT-23	W
MSOP	Y
HMSOP	YE
TSOT	WT
SC-70	C

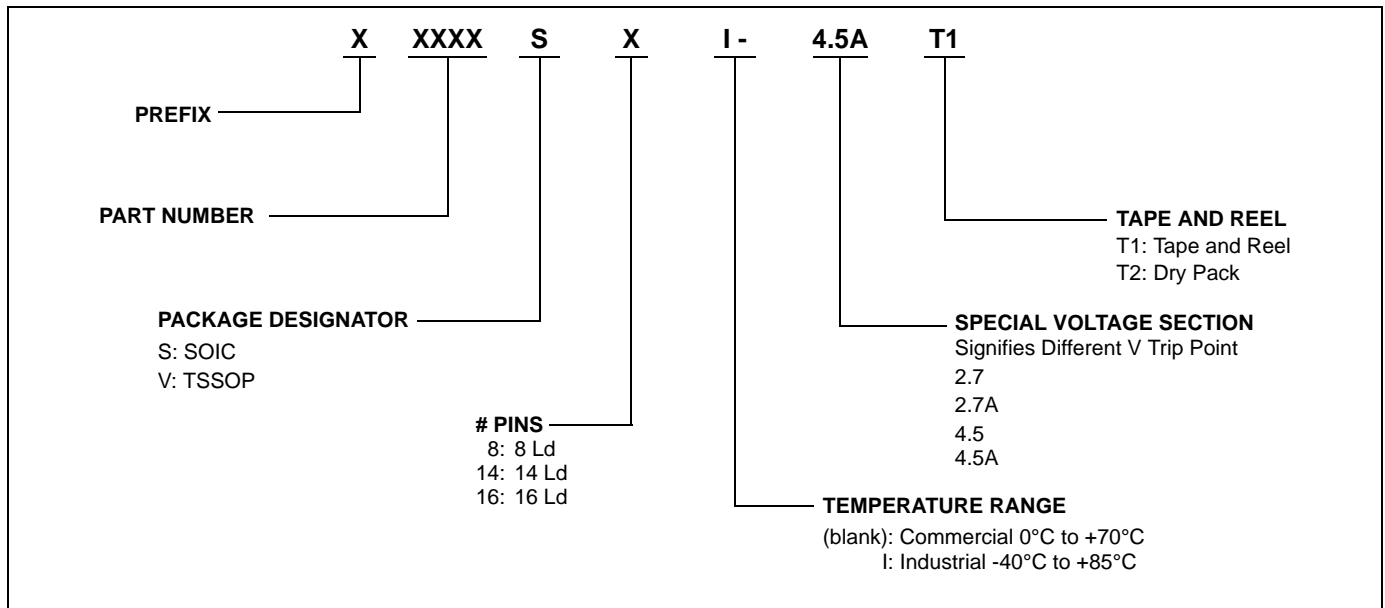
Nomenclature Guides

X Types

System Management Products (SMP)

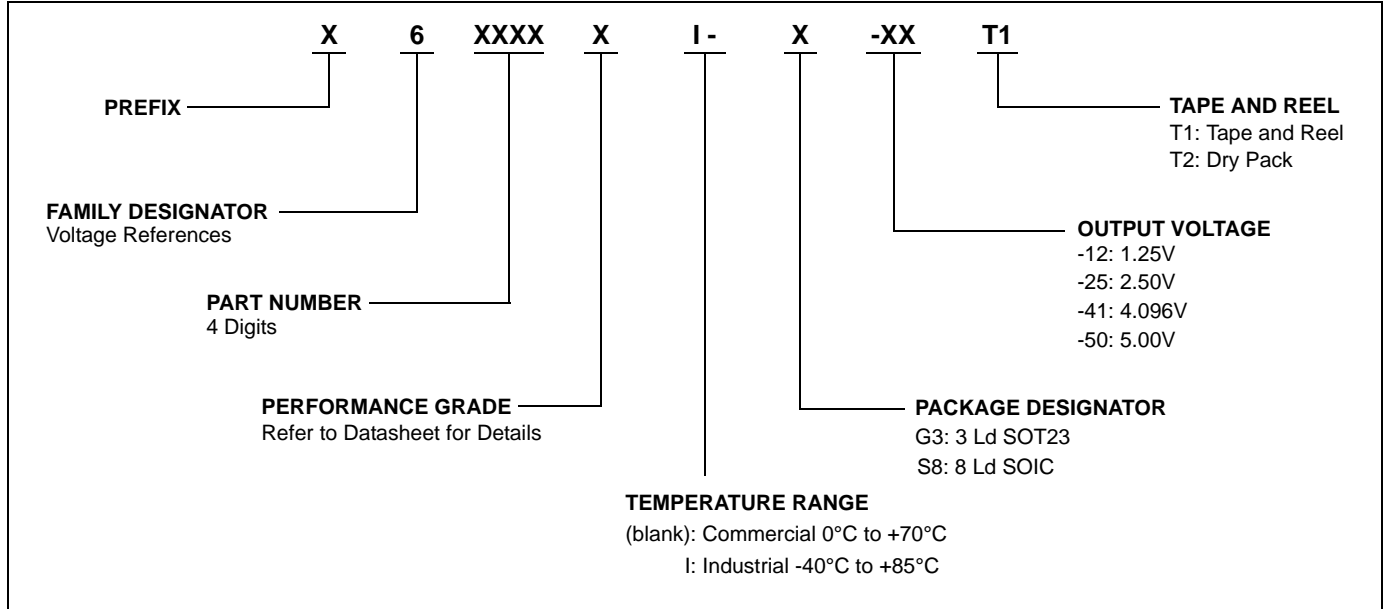


Real Time Clocks (RTC)

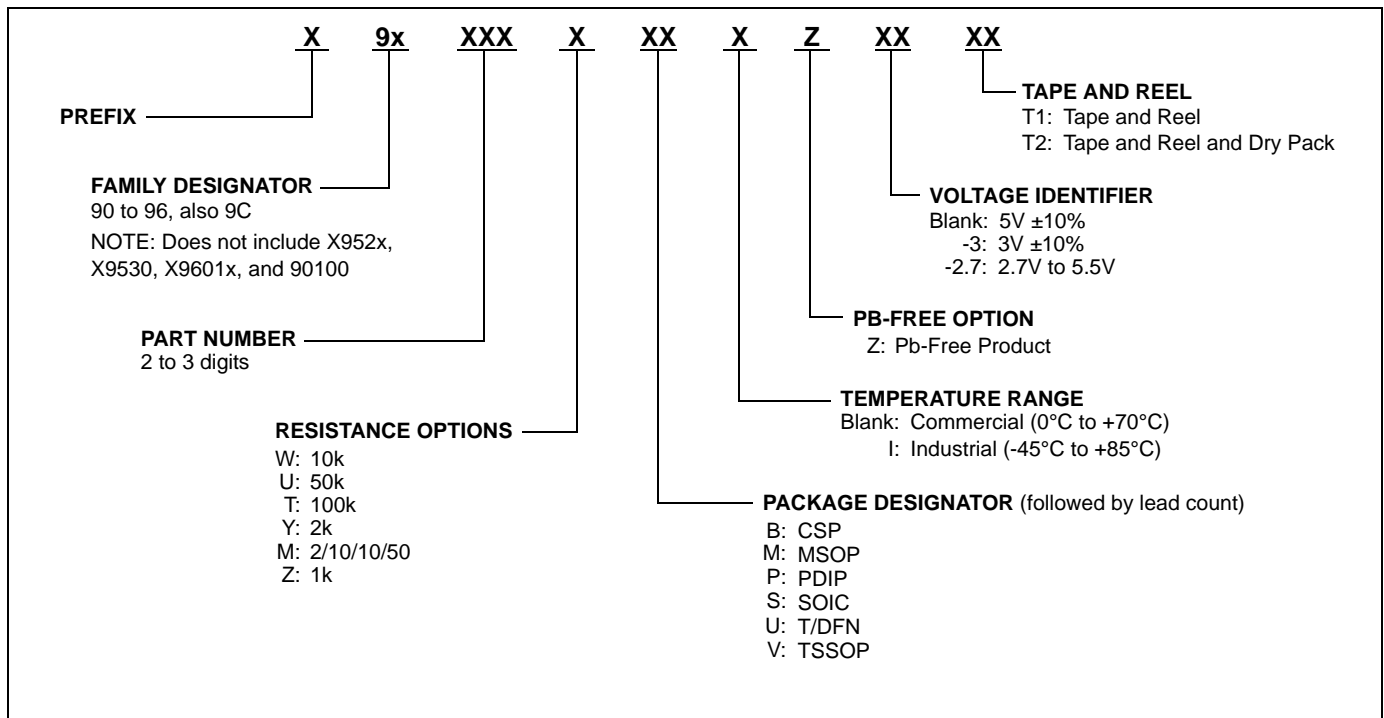


Nomenclature Guides

Voltage References (VREFs)

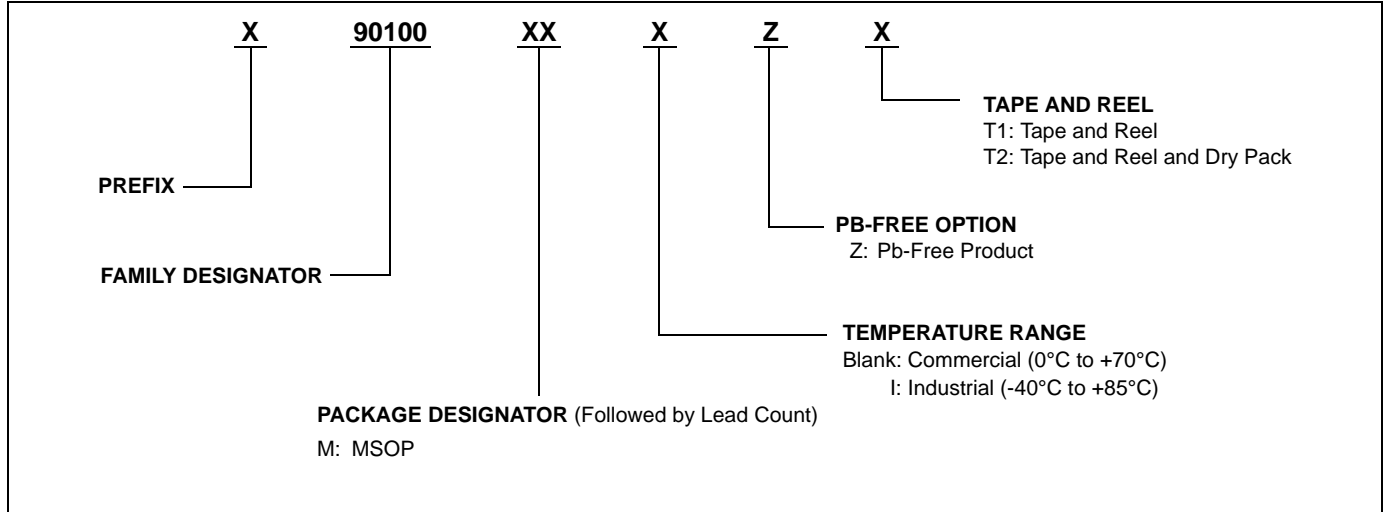


Digitally Controlled Potentiometers (DCPs)

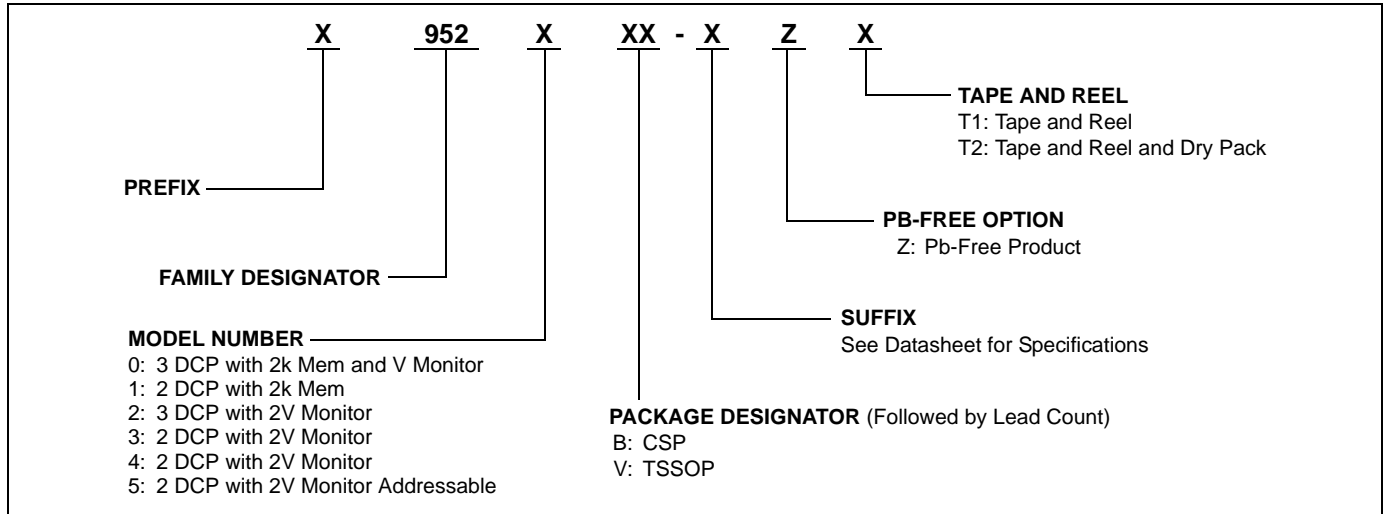


Nomenclature Guides

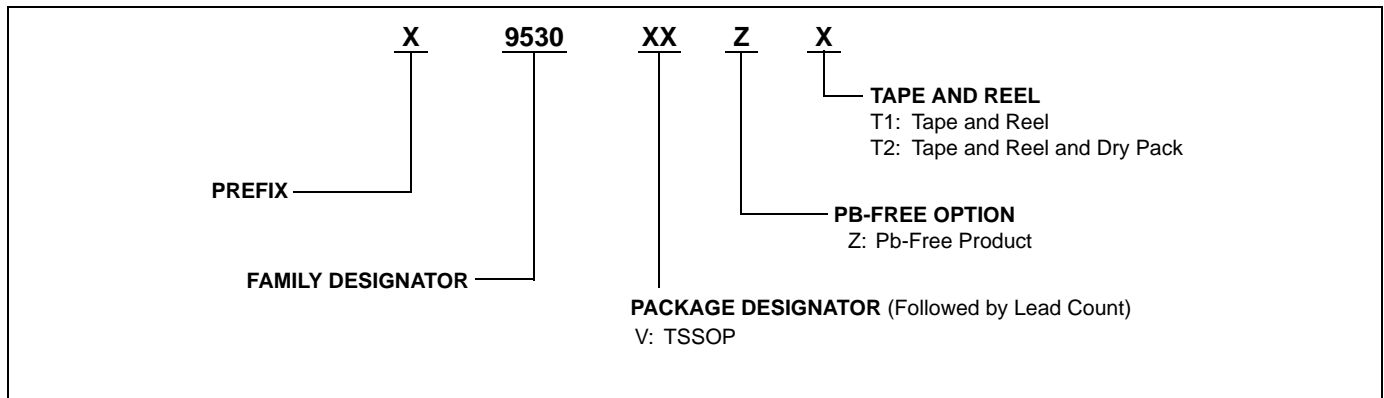
Digitally Controlled Capacitors (DCCs)



Bias and Control for Laser Diode with Integrated DCP

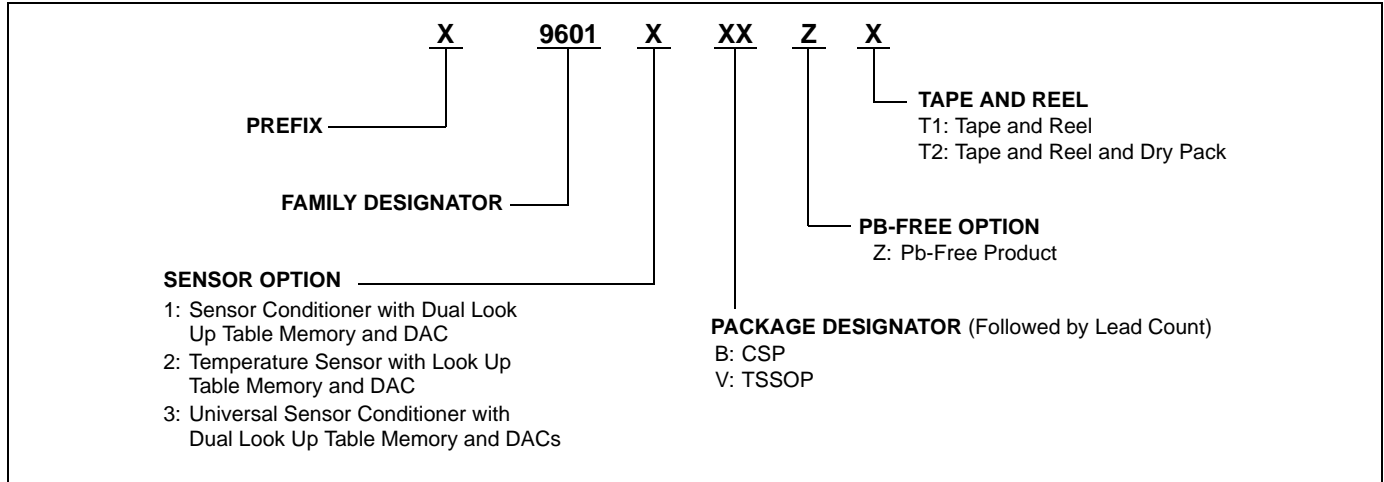


Bias and Control for Laser Diode

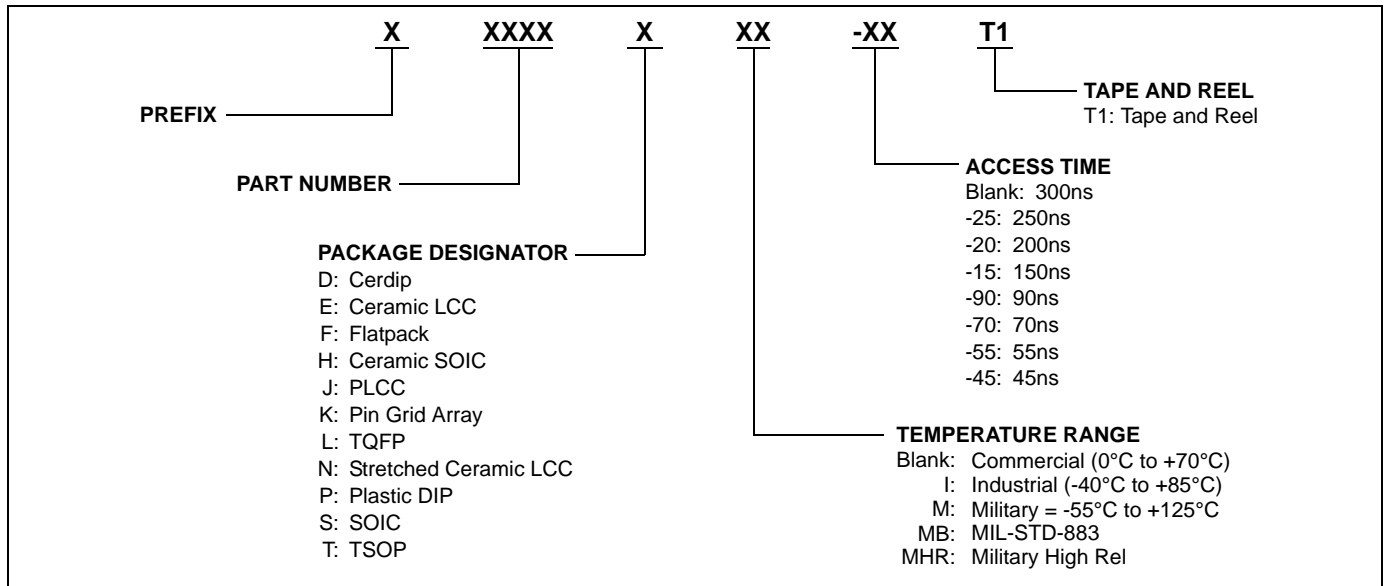


Nomenclature Guides

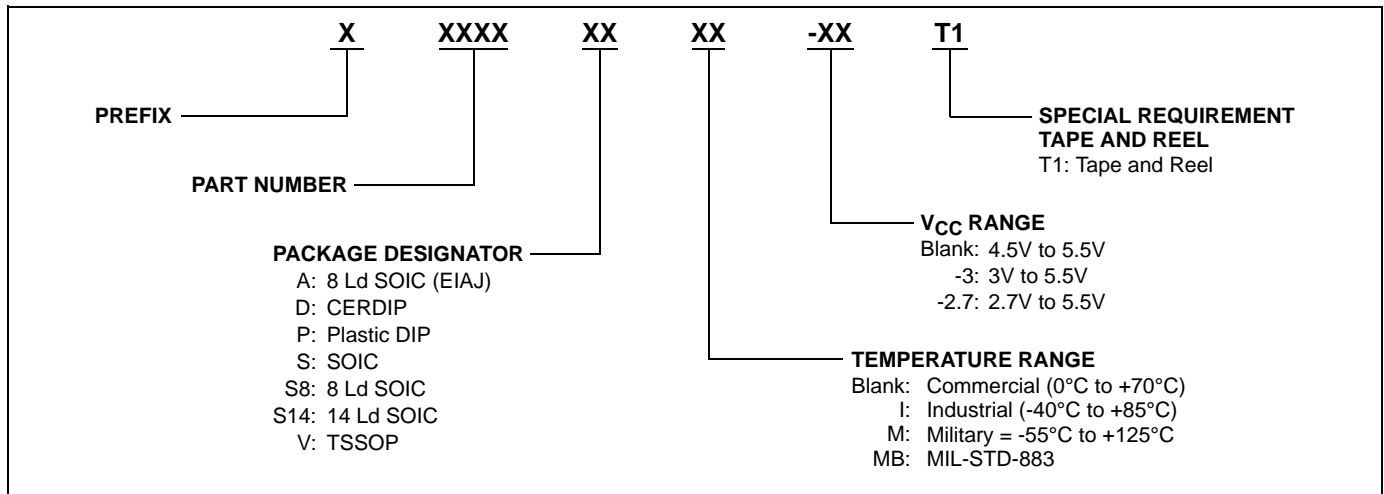
General Purpose Sensor Conditioners with Look-Up Table Memory



Parallel E²PROM

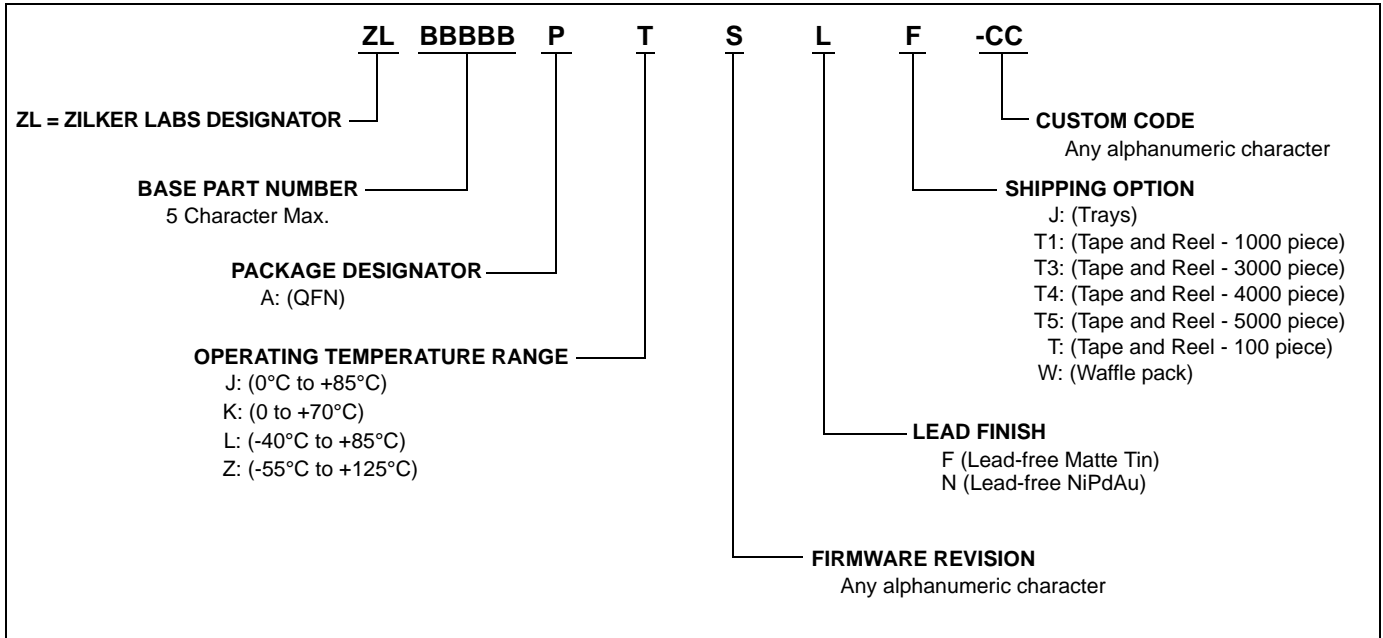


Serial E²PROM

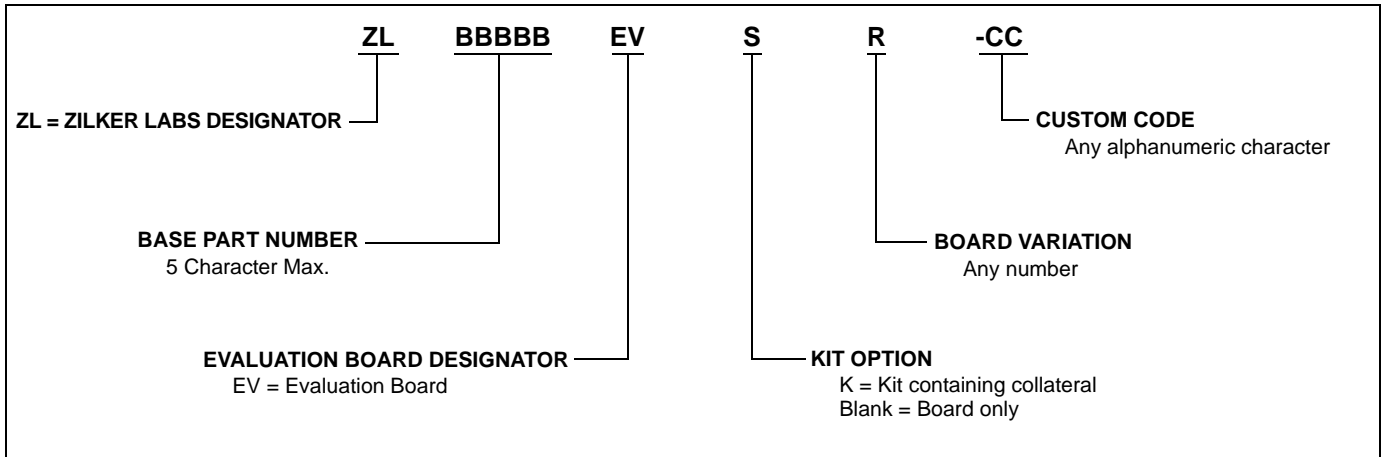


Nomenclature Guides

ZL Types

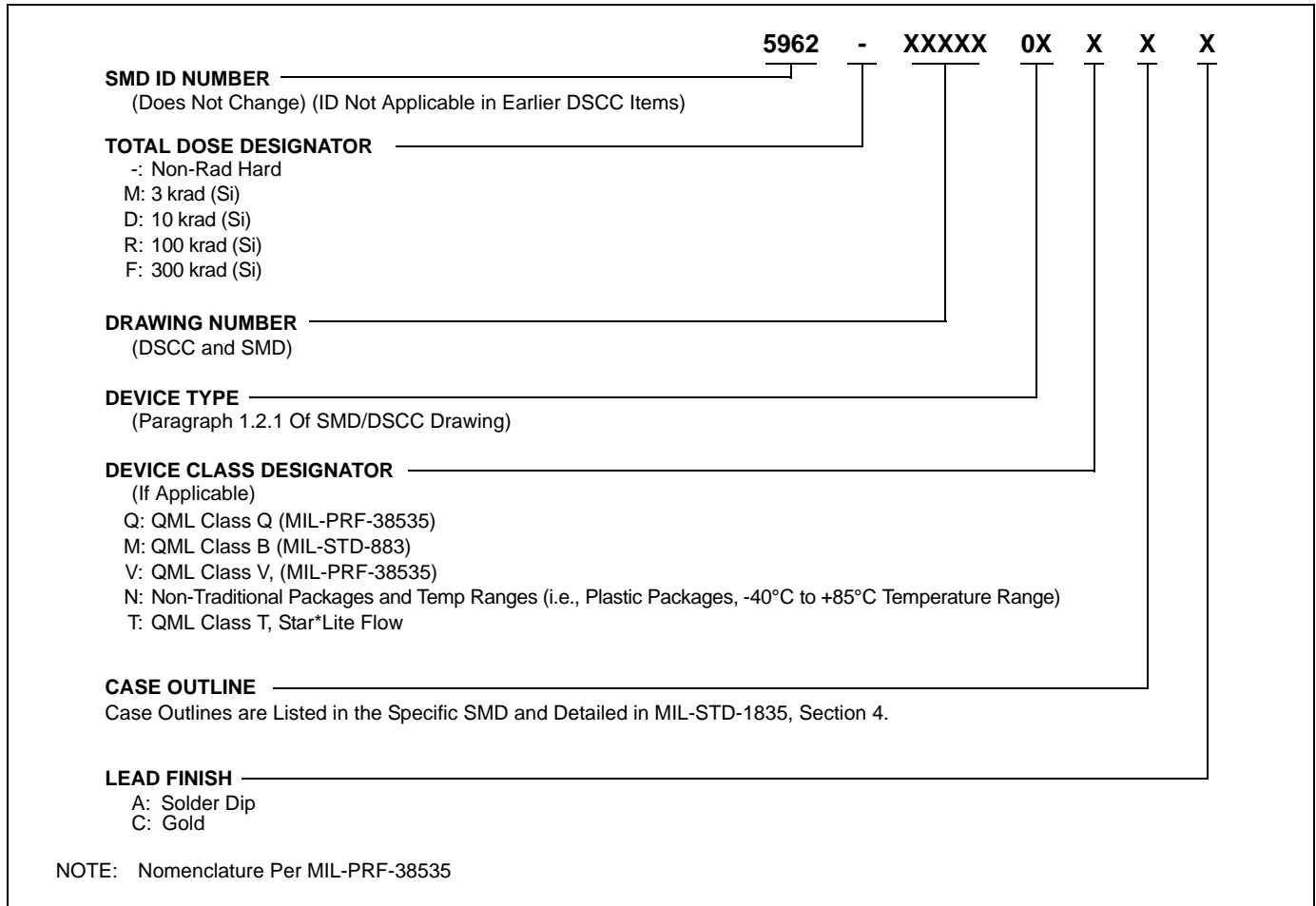


ZL Evaluation Boards

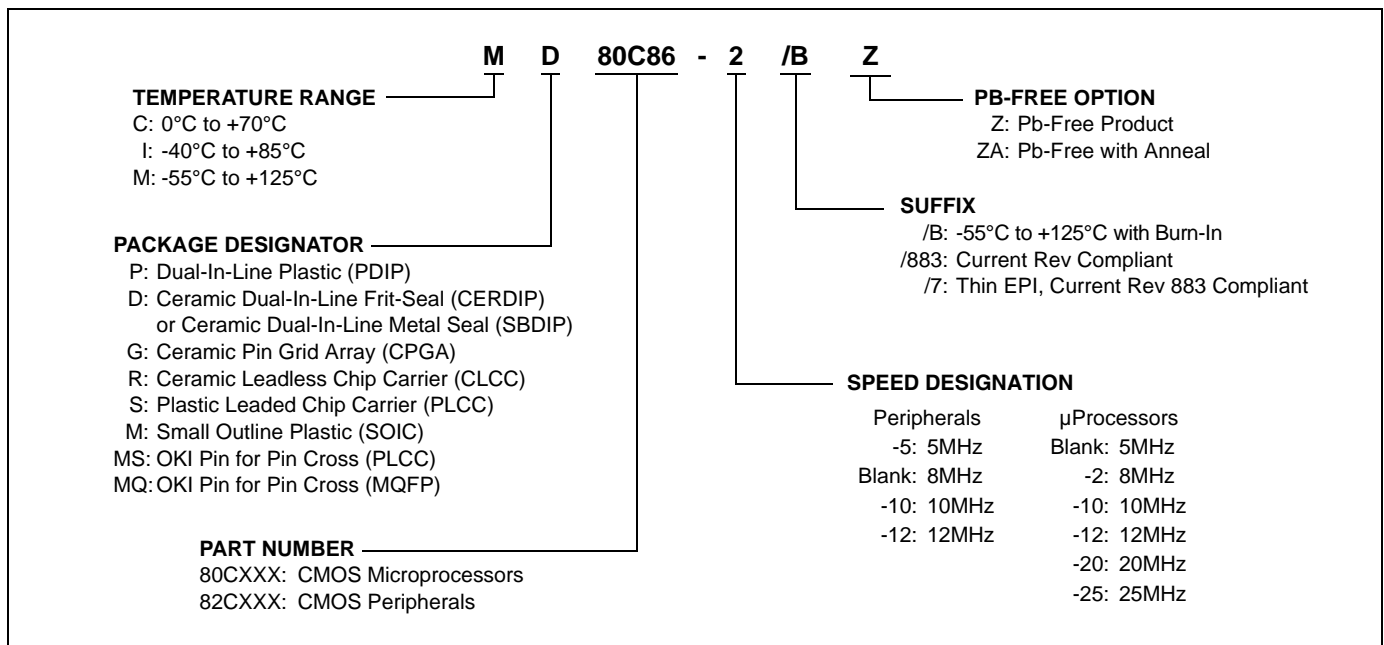


Intersil Legacy Nomenclatures

5962 SMD/DSCC - QML Types

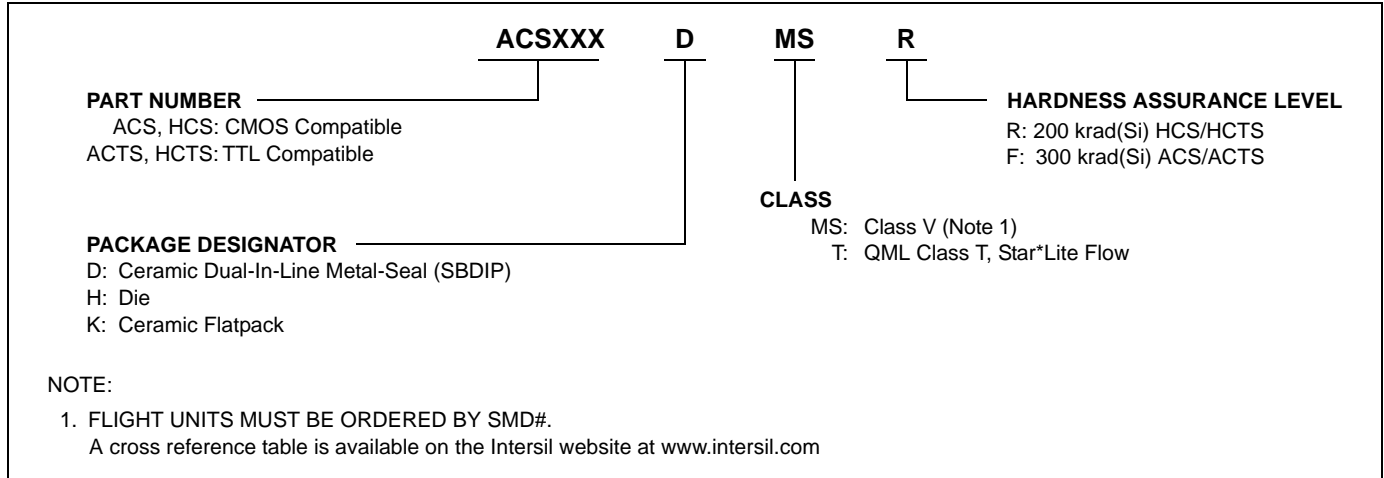


80C, 82CXXX Types

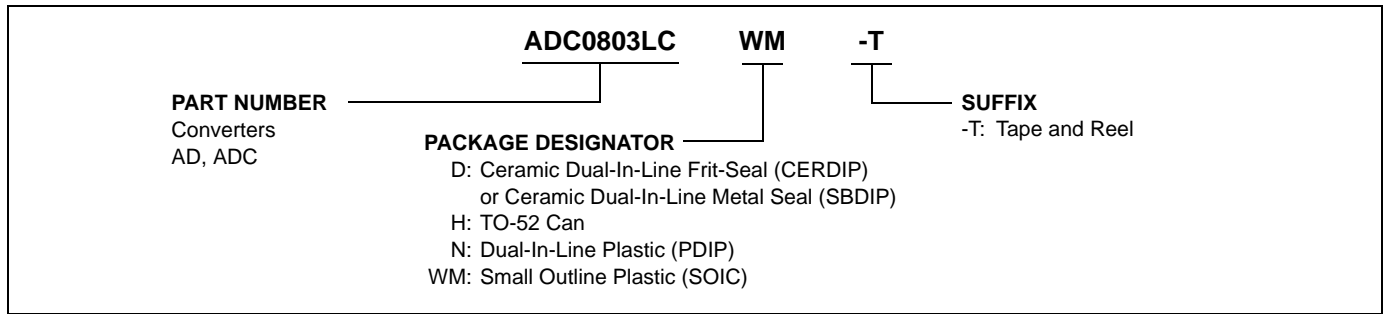


Nomenclature Guides

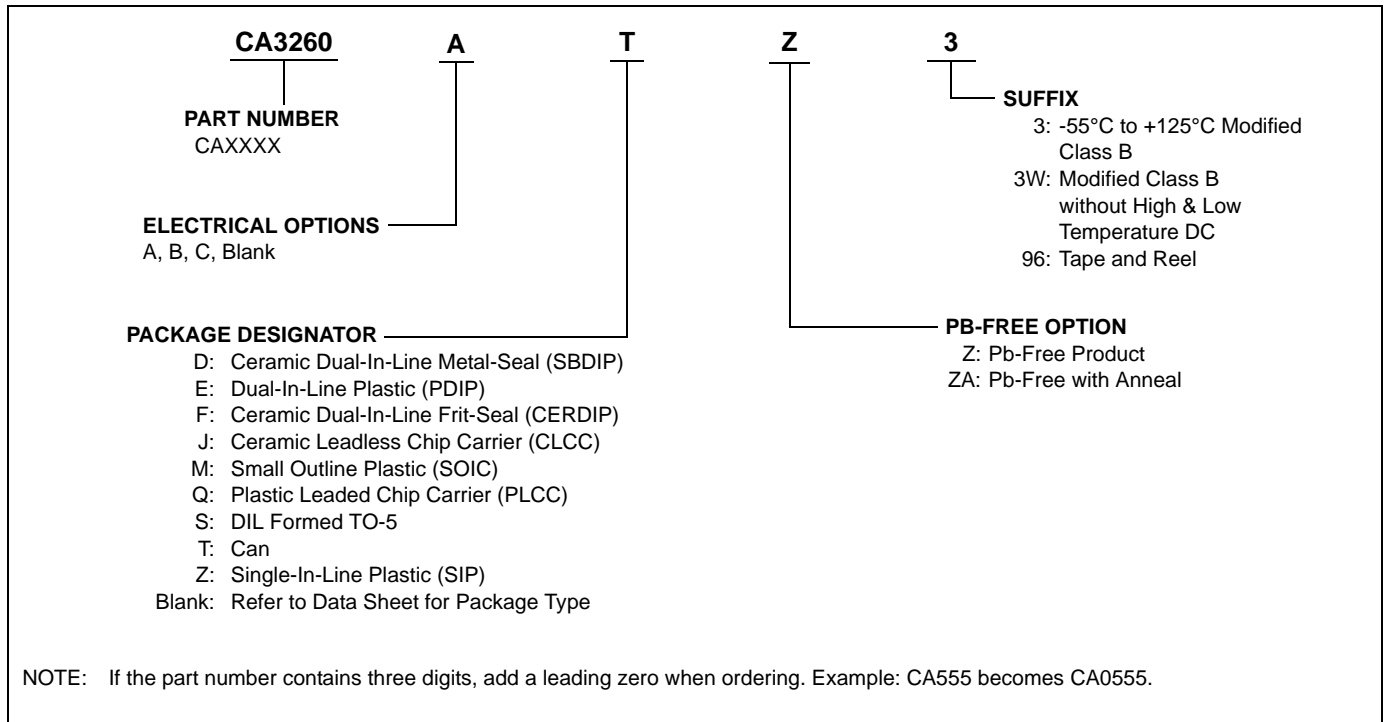
ACS, ACTS, HCS, HCTS Radiation Hardened Types



AD Types

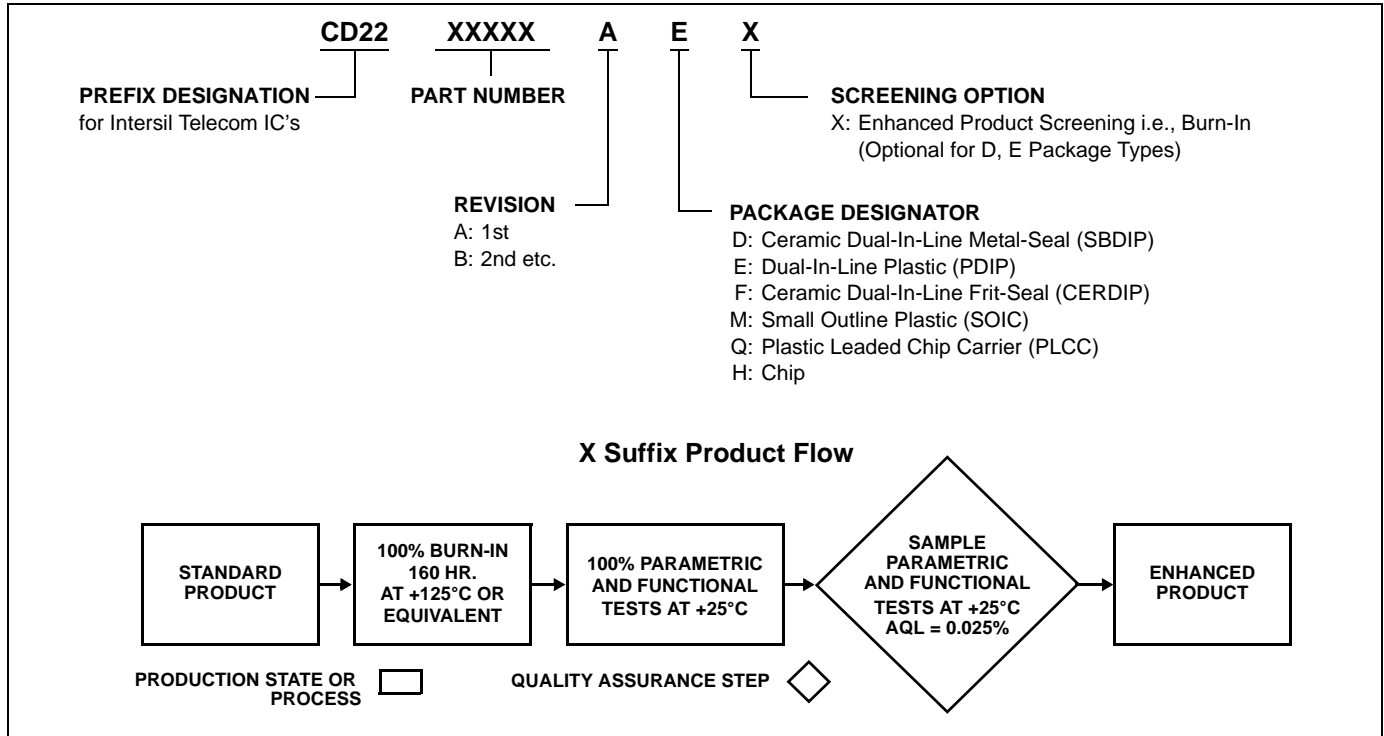


CA Types

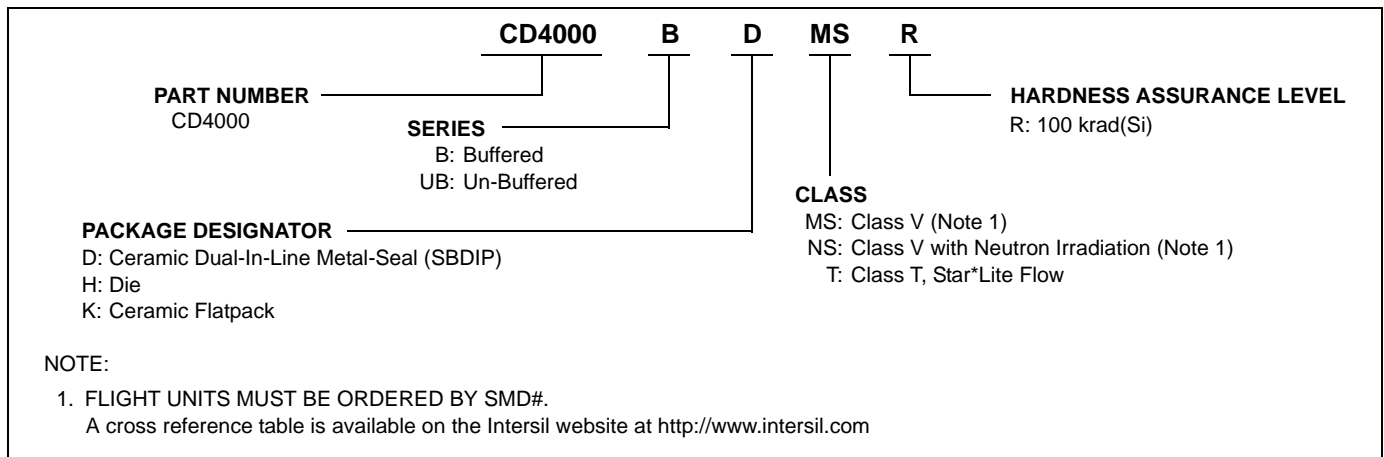


Nomenclature Guides

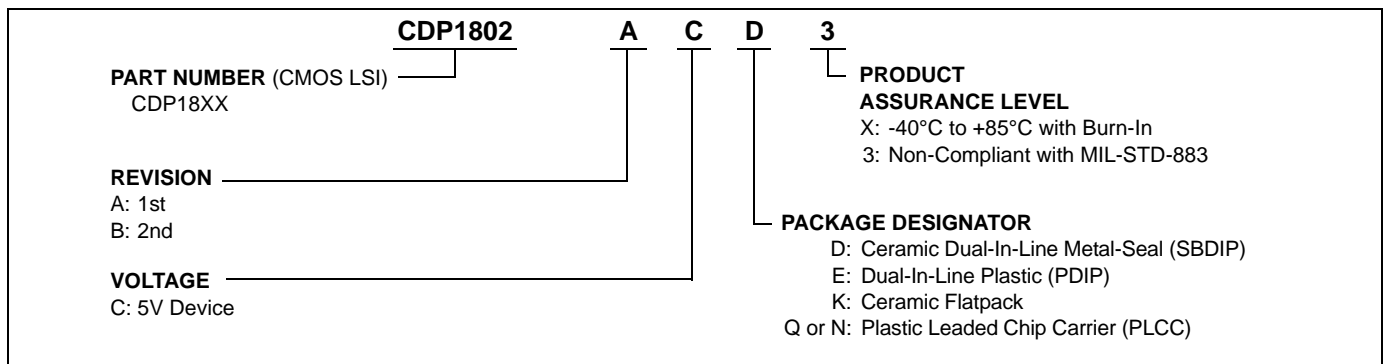
CD22XXX Types



CD4000 Radiation Hardened Types

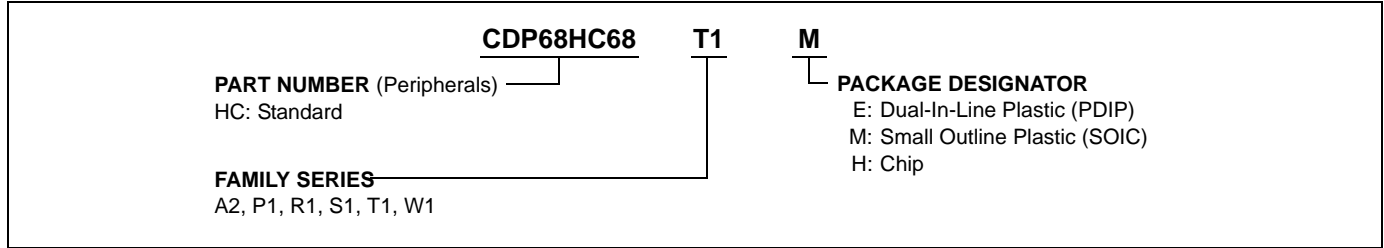


CDP Types

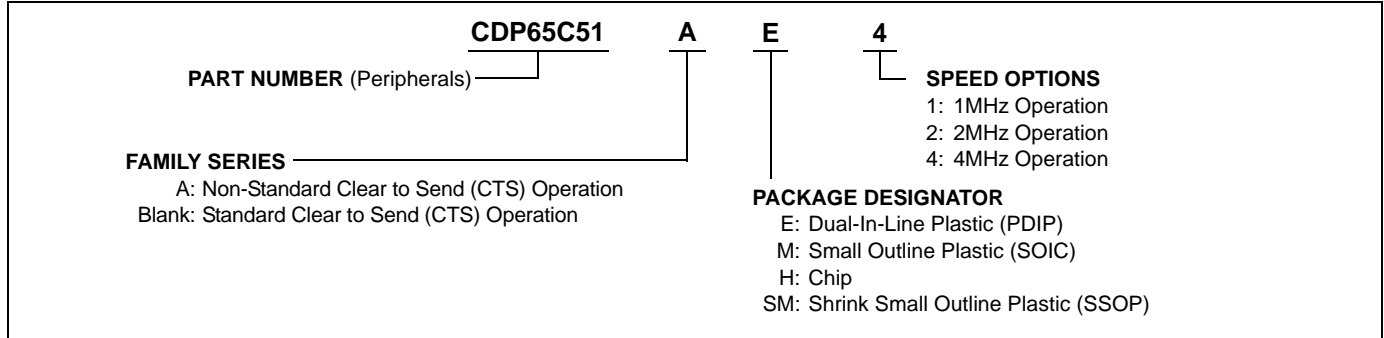


Nomenclature Guides

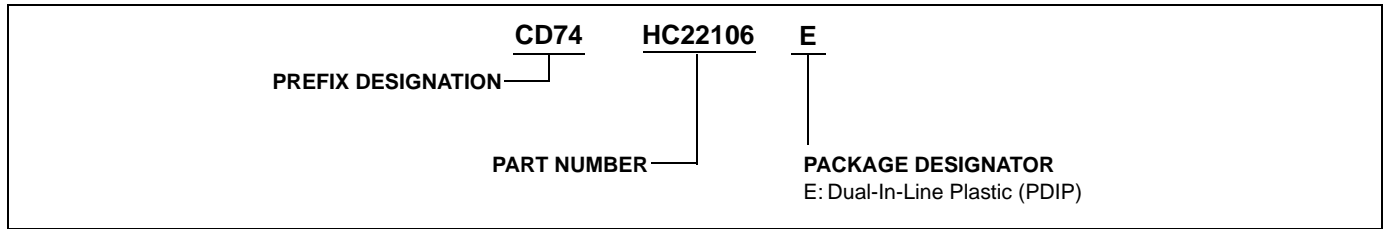
CDP68HC68 Types



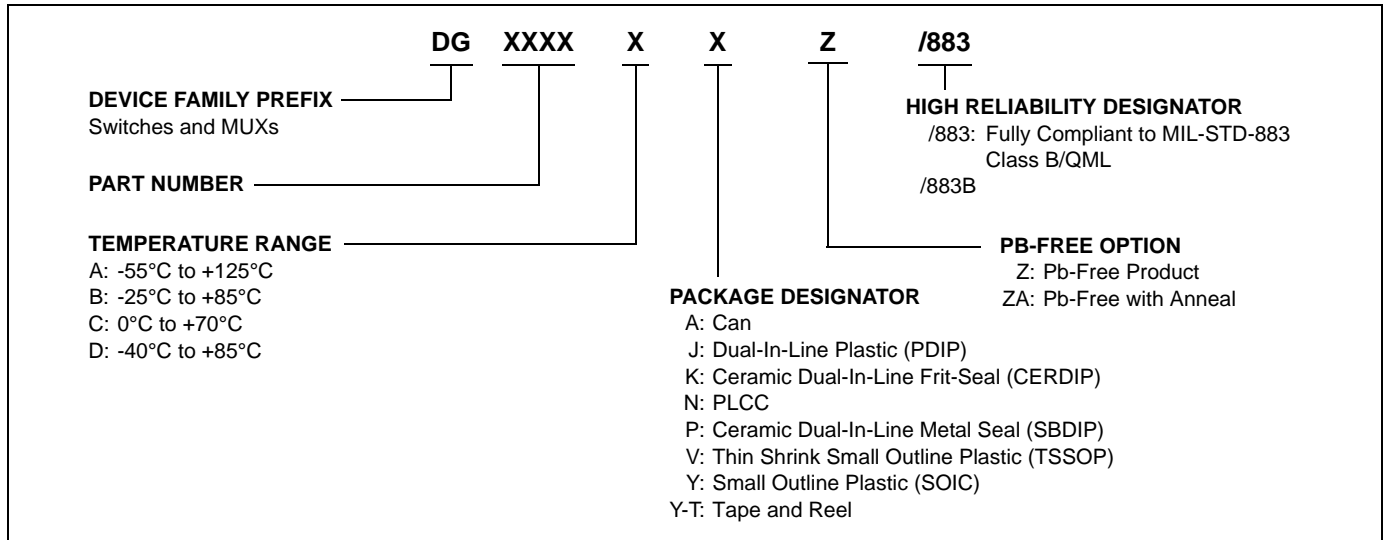
CDP65C51 Types



CD74HC Types



DG Types



Nomenclature Guides

HX Types

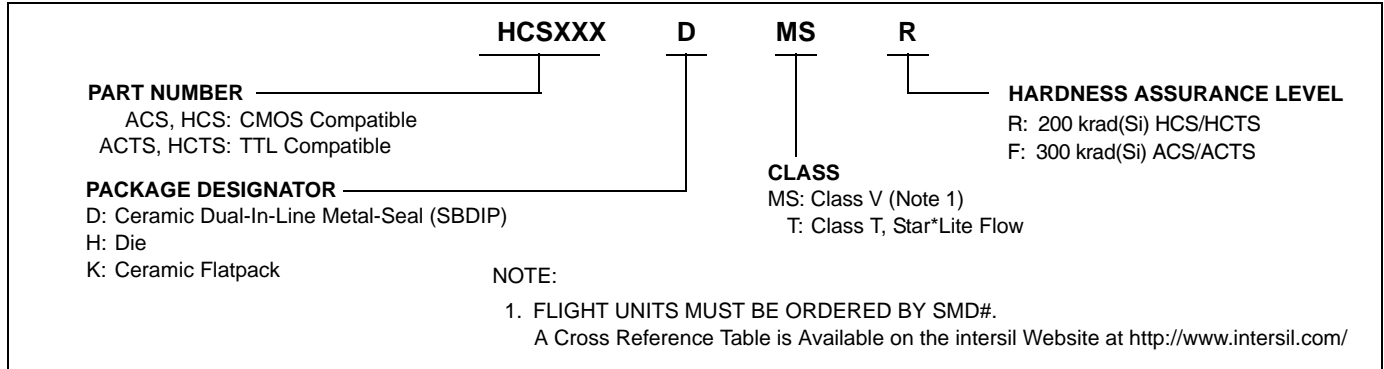
<p>PREFIX ————— H A</p> <p>FAMILY —————</p> <p>A: Analog C: Communications D: Digital I: Interface M: Memory V: Analog High Voltage</p> <p>PACKAGE DESIGNATOR —————</p> <p>1: Ceramic Dual-In-Line Frit-Seal (CERDIP) 1B: Ceramic Dual-In-Line Metal-Seal (SBDIP) 2: Can 3: Dual-In-Line Plastic (PDIP) 4: Ceramic Leadless Chip Carriers (CLCC) 4P: Plastic Leadless Chip Carrier (PLCC) 6: Narrow Dual-In-Line Plastic (PDIP) or Ceramic Dual-In-Line Frit-Seal (CERDIP) 7: 8 Lead Ceramic Dual-In-Line Frit-Seal (CERDIP) 9P: Small Outline Plastic (SOIC) 0: Chip</p> <p>NOTE: If the package designator is 2 characters the hyphen is omitted from the part number.</p>	<p>1 - 5134</p> <p>PART NUMBER</p> <p>PERFORMANCE GRADE A, B: High Performance C: Relaxed Specification S: Very High Speed</p> <p>NOTE: Applies to HA, HD and HM products only.</p> <p>TEMPERATURE RANGE</p> <p>-2: -55°C to +125°C -4: -25°C to +85°C -5: 0°C to +75°C -6: +25°C Chip Probe -7: Dash-7 High Reliability Commercial Product 0°C to +75°C, Includes 96 hour Burn-In -8: -55°C to +125°C Intersil Class B Equivalent Devices for use in Military and Flight Systems -9: -40°C to +85°C /883: Fully Compliant to MIL-STD-883, Class B/QML BXXXX: Customer Specific Screening RXXXX: Customer Specific Screening SXXXX: Customer Specific Screening</p>	<p>A -2 Z 96</p> <p>SUFFIX 96: Tape and Reel Option for SOIC, PLCC X96: Tape and Reel Option for SOIC, PLCC EVAL: Evaluation Platform</p> <p>PB-FREE OPTION Z: Pb-Free Product ZA: Pb-Free with Anneal</p>
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HX, HXX Types

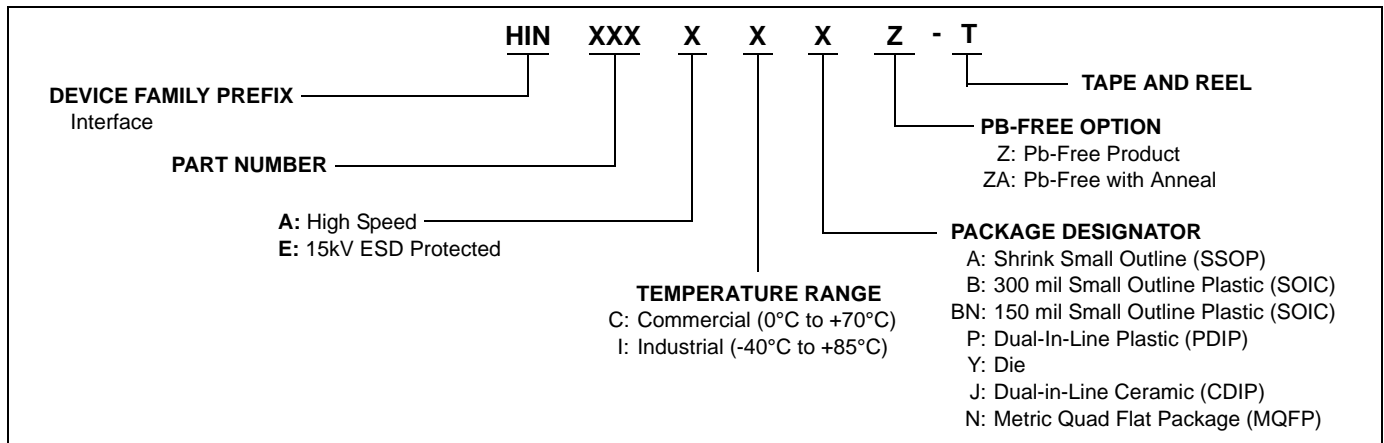
<p>PREFIX ————— H A</p> <p>FAMILY —————</p> <p>A: Analog C: Communications FA: Ultra-High Frequency Analog I: Data Acquisition, DSP Function-Specific V: Analog High Voltage</p>	<p>4314B</p> <p>PART NUMBER</p> <p>TEMPERATURE RANGE C: 0°C to +70°C I: -40°C to +85°C M: -55°C to +125°C</p> <p>PACKAGE DESIGNATOR —————</p> <p>A: Shrink Small Outline Plastic (SSOP) B: Small Outline Plastic (SOIC) D: Ceramic Dual-In-Line Metal-Seal (SBDIP) H: Plastic Small Outline Transistor (SOT) J: Ceramic Dual-In-Line Frit-Seal (CERDIP) L: Ceramic Leadless Chip Carrier (CLCC) M: Plastic Leadless Chip Carrier (PLCC) N: Thin Quad Flatpack (TQFP), or Metric Quad Flatpack (MQFP) Q: Metric Plastic Quad Flatpack (MQFP), or Plastic Quad Flatpack (PQFP) P: Dual-In-Line Plastic (PDIP) T: Can Y: Chip (Commercial Visual) W: Wafer</p>	<p>C B Z 96</p> <p>SUFFIX /883: Fully Compliant to MIL-STD-883 Class B/QML 96: Tape and Reel -T: Tape and Reel EVAL: Evaluation Platforms</p> <p>PB-FREE OPTION Z: Pb-Free Product ZA: Pb-Free with Anneal</p>
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Nomenclature Guides

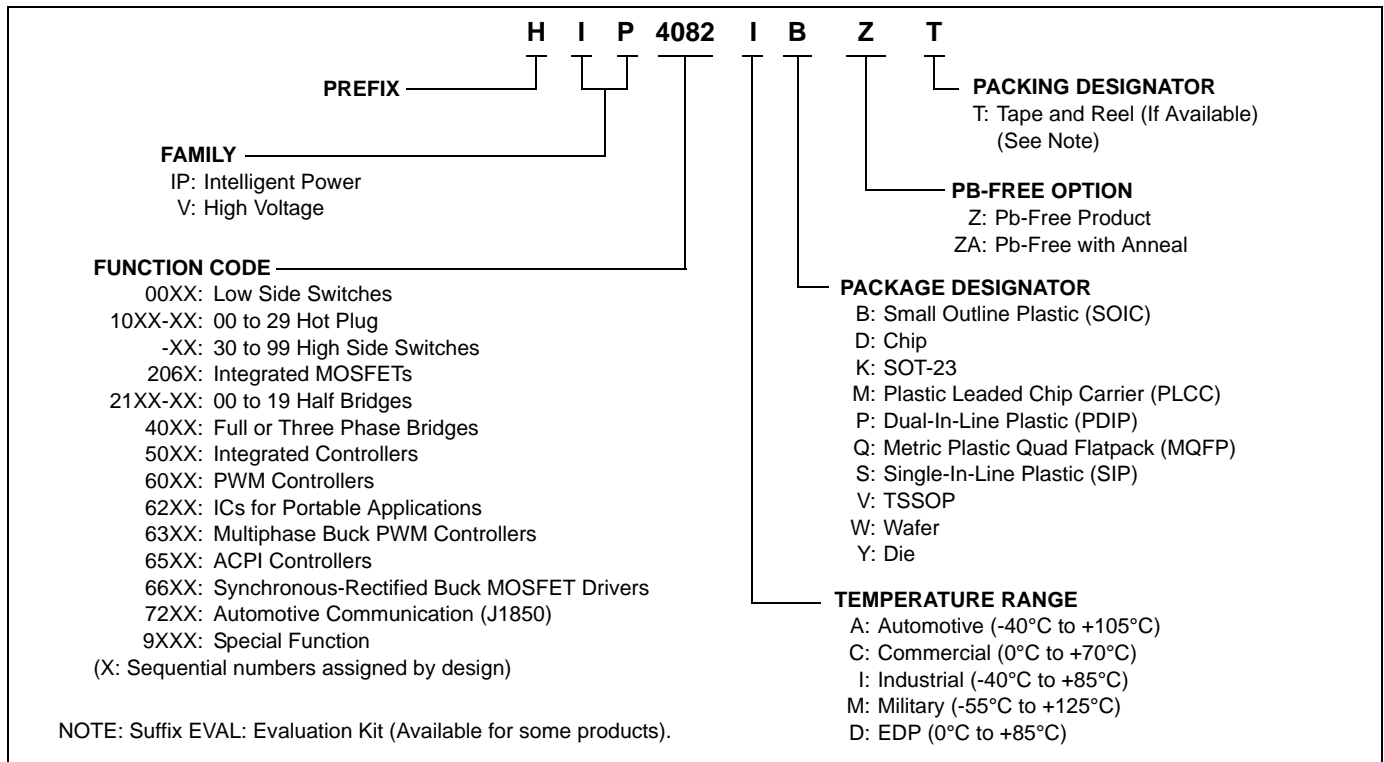
HCS, HCTS, ACS, ACTS, Radiation Hardened Types



HIN Types

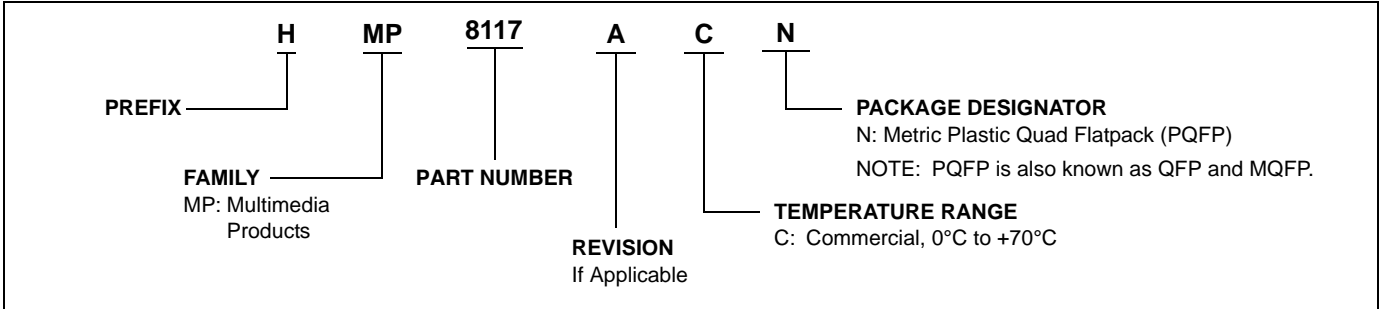


HIP Types

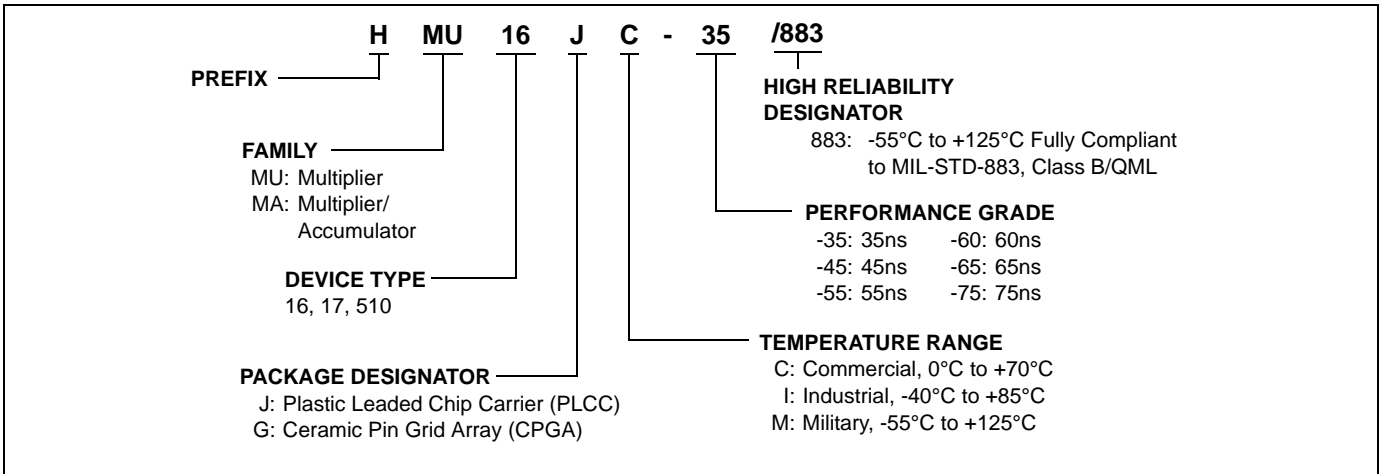


Nomenclature Guides

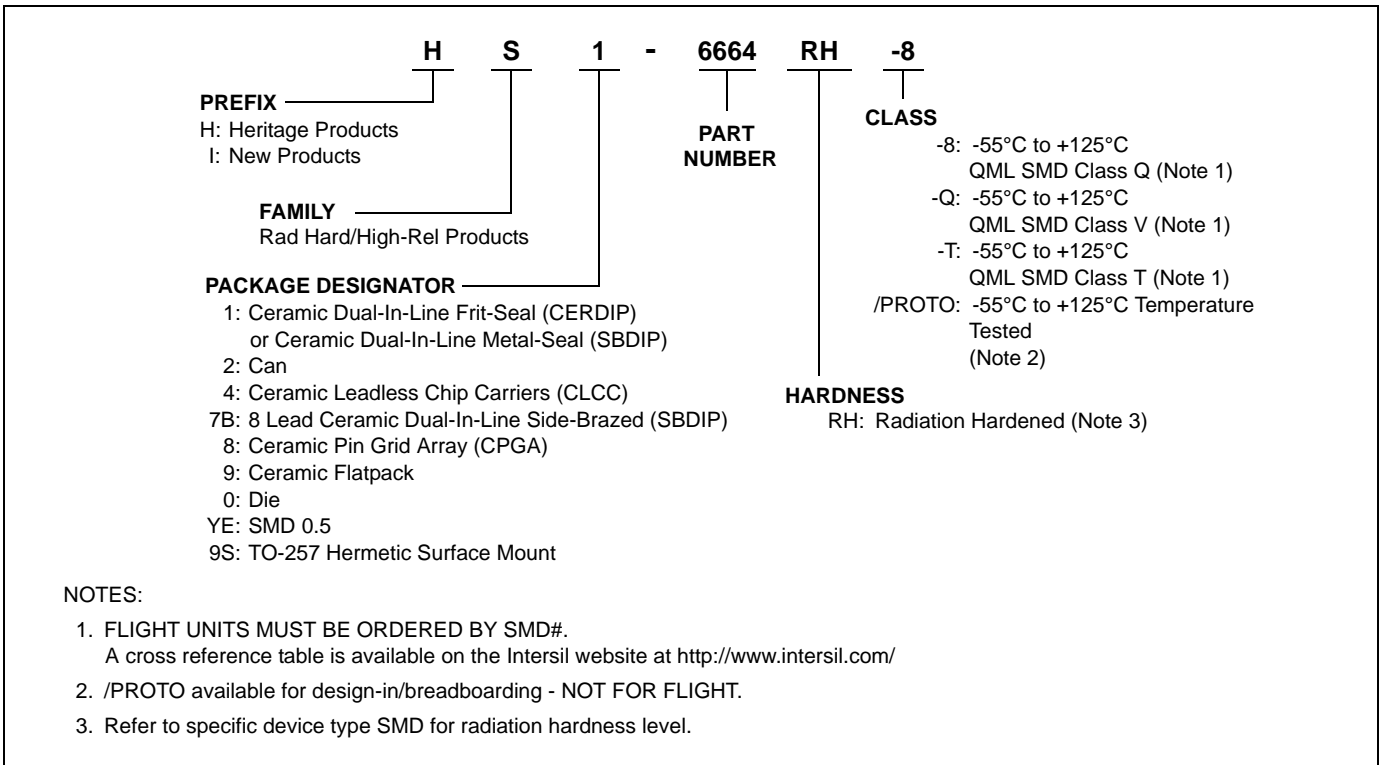
HMP Types



HMU/HMA Types

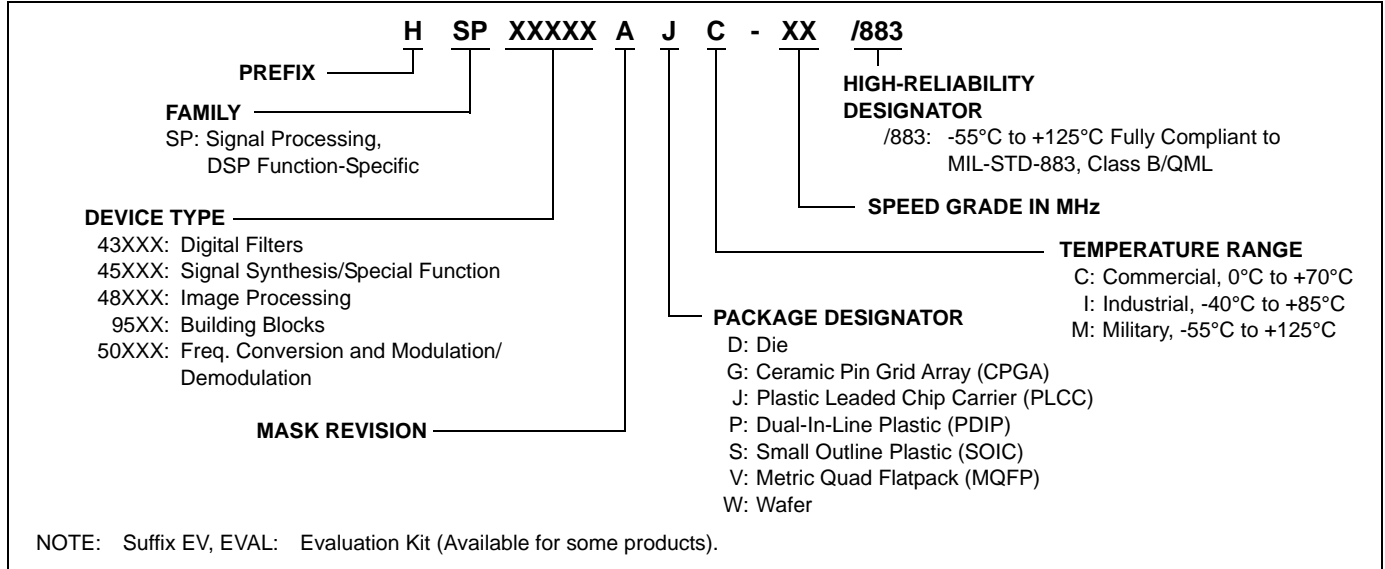


HS/IS Radiation Hardened Types

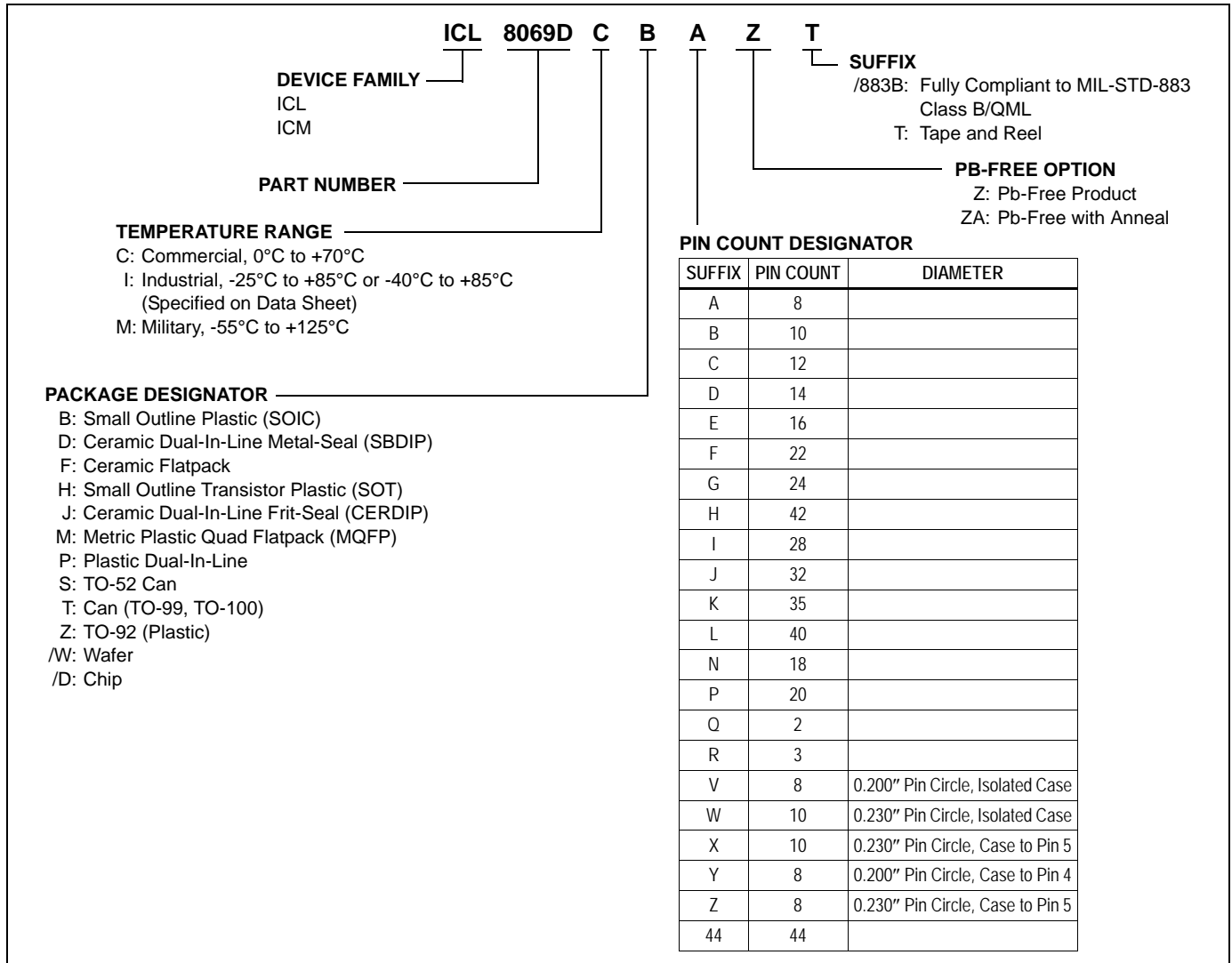


Nomenclature Guides

HSP Types

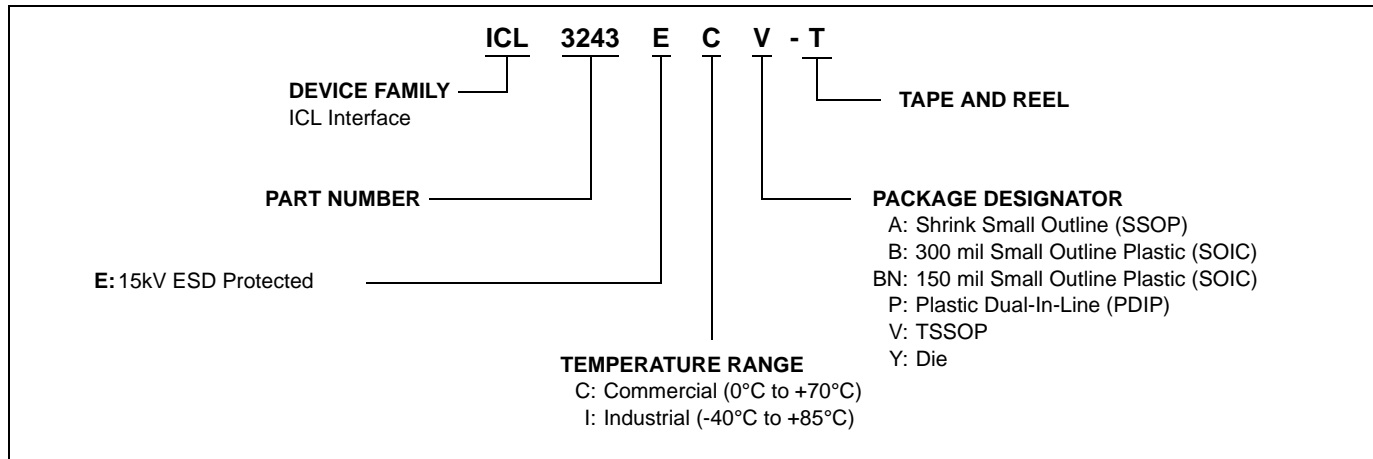


ICL, ICM Types



Nomenclature Guides

ICL Types (Interface Circuits)



JM JAN-QML Types

